

ABSTRACT

The present invention relates to electroless plating of a platinum-rhodium alloy onto a substrate. More particularly, this invention pertains to an aqueous platinum and rhodium plating bath, a process for plating a uniform coating of a platinum-rhodium alloy onto various substrates using an electroless plating composition, and a platinum-rhodium plated article formed therefrom. This process is suitable for the deposition of a platinum-rhodium alloy on virtually any material of any geometrical shape, including fibers and powders.

094489 070600